

EFD 15/8/5 Core and accessories

 Series/Type:
 B66413, B66414

 Date:
 June 2019

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EFD 15/8/5

Core

- E core with flattened, lower center leg for especially flat transformer design
- For DC/DC converters
- Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 2.27 \text{ mm}^{-1}$ $I_e = 34 \text{ mm}$ $A_e = 15 \text{ mm}^2$ $A_{min} = 12.2 \text{ mm}^2$ $V_e = 510 \text{ mm}^3$

15±0,4

FEK0417-2

Approx. weight 2.8 g/set

Ungapped

Material	A _L value nH	μ _e	P _V W/set	Ordering code
N49	600 +30/–20%	1080	< 0.11 (50 mT, 500 kHz, 100 °C)	B66413G0000X149
N87	780 +30/–20%	1400	< 0.28 (200 mT, 100 kHz, 100 °C)	B66413G0000X187
N97	820 +30/-20%	1480	< 0.23 (200 mT, 100 kHz, 100 °C)	B66413G0000X197

Other A_L values/air gaps and materials available on request – see Processing remarks on page 5.

Gapped (A_L values/air gaps examples)

Material	A _L value nH	μ _e	g approx. mm	Ordering code ** = 87 (N87) = 97 (N97)
N87,	50 ±5%	90	0.46	B66413U0050J1**
N97	100 ±10%	180	0.17	B66413U0100K1**
	125 ±10%	225	0.12	B66413U0125K1**
	160 ±15%	288	0.08	B66413U0160L1**

The A_L value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

	Calculation	factors	(for formulas,	see "E cores:	general information")
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Material	Relationship air gap – A _L		Calculation o	f saturation cu	ırrent	
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)
N87	29.7	-0.676	44.2	-0.796	33.2	-0.873

Validity range:

K1, K2: 0.10 mm < s < 1.00 mm K3, K4: 30 nH < A_L < 280 nH 5±0,15



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Accessories

Coil former

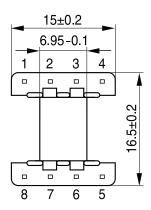
Material:	GFR thermosetting plastic (UL 94 V-0, insulation class to IEC 60085: F ≙ max.operating temperature 155 °C), color code black Sumikon PM 9630 [®] [E41429 (M)], SUMITOMO BAKELITE CO LTD
Resistance to	to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s
Winding: Pins:	see Processing notes, 2.1 Squared pins

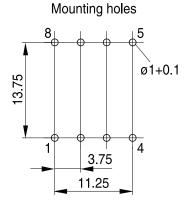
Yoke

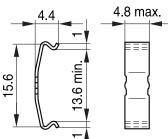
Material: Stainless spring steel (0.25 mm)

Coil former					Ordering code
Sections	A _N mm ²	l _N mm	A_R value $_{\mu\Omega}$	Pins	
1	15.5	35.9	79.7	8	B66414W1008D001
Yoke (order	ing code per pie	ece, 2 are requi	ired)		B66414B2000X000

Coil former



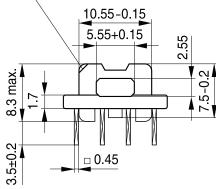


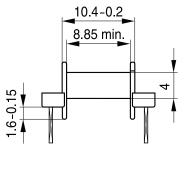


Yoke

FEK0271-J

Pin 1 marking





FEK0418-A-E

Please read Cautions and warnings and Important notes at the end of this document. B66414



B66414

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Accessories

SMD

SMD coil former with J terminals

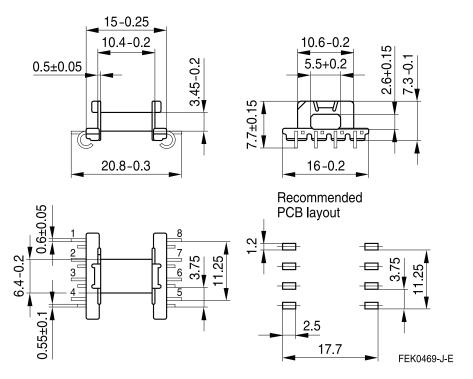
Material:	GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085: F ≙ max. operating temperature 155 °C), color code black Laperos E 130i [E106764 (M)], POLYPLASTICS CO LTD Vectra E 130i [E83005 (M)], CELANESE INTERNATIONAL CORP.
Solderability:	to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s
Resistance to	soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s
Winding:	see Processing notes, 2.1
Yoke	
Material:	Stainless spring steel (0.25 mm)
Mounting:	Preferred assembly direction from the top
Cover plate	
For marking a	nd improved processing on assembly machines.
	See under coil former for material and resistance to soldering heat.
Matarial	Sumite Super E4008® [E54705 (M)] SUMITOMO CHEMICAL COLTD

Material: Sumika Super E4008[®] [E54705 (M)], SUMITOMO CHEMICAL CO LTD

Coil former					Ordering code
Sections	A _N mm ²	l _N mm	A_R value $\mu\Omega$	Terminals	
1	18.1	35.1	66.7	8	B66414B6008T001
Yoke (order	ring code pe	r piece, 2 are	required)		B66414B2000X000
Cover plate					B66414A7000X000

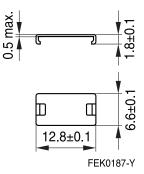
Coil former

Yoke



4.4 4.8 max.

Cover plate



Please read *Cautions and warnings* and *Important notes* at the end of this document.

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Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_L value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "*Processing notes*", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for TDK Electronics products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A _e	Effective magnetic cross section	mm ²
AL	Inductance factor; $A_L = L/N^2$	nH
A _{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A _R	Resistance factor; $A_R = R_{Cu}/N^2$	μΩ = 10 ⁻⁶ Ω
В	RMS value of magnetic flux density	Vs/m², mT
ΔB	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m², mT
ΔÂ	Peak value of flux density deviation	Vs/m², mT
B _{DC}	DC magnetic flux density	Vs/m², mT
B _R	Remanent flux density	Vs/m², mT
B _S	Saturation magnetization	Vs/m², mT
C ₀	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
Ea	Activation energy	J
f	Frequency	s ^{−1} , Hz
f _{cutoff}	Cut-off frequency	s−1, Hz
f _{max}	Upper frequency limit	s ^{−1} , Hz
f _{min}	Lower frequency limit	s ^{−1} , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f _{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H _{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ _i ²	Relative hysteresis coefficient	10 ⁻⁶ cm/A
I	RMS value of current	А
I _{DC}	Direct current	A
Î	Peak value of current	А
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L ₀	Inductance of coil without core	Н
L _H	Main inductance	Н
L _p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P _{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P _V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_L)	
R	Resistance	Ω
R _{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_{h}	R _h change	Ω
R _i	Internal resistance	Ω
R _p	Parallel loss resistance of a core	Ω
R _s	Series loss resistance of a core	Ω
R _{th}	Thermal resistance	K/W
R _V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	к
Т _С	Curie temperature	°C
t	Time	s
t _v	Pulse duty factor	
tan δ	Loss factor	
tan δ _l	Loss factor of coil	
tan δ _r	(Residual) loss factor at $H \rightarrow 0$	
tan δ _e	Relative loss factor	
tan δ_h	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z _n	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e/A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit			
α	Temperature coefficient (TK)				
α_{F}	Relative temperature coefficient of material	1/K			
α _e	Temperature coefficient of effective permeability	1/K			
ε _r	Relative permittivity				
Φ	Magnetic flux	Vs			
1	Efficiency of a transformer				
JB	Hysteresis material constant	mT ⁻¹			
li	Hysteresis core constant	A-1H-1/2			
ls	Magnetostriction at saturation magnetization				
u	Relative complex permeability				
uO	Magnetic field constant	Vs/Am			
la	Relative amplitude permeability				
Чарр	Relative apparent permeability				
le.	Relative effective permeability				
ι _i	Relative initial permeability				
ι _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)				
¹ p"	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)				
ι ι _r	Relative permeability				
^u rev	Relative reversible permeability				
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)				
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)				
[⊥] tot	Relative total permeability				
	derived from the static magnetization curve				
)	Resistivity	Ωm^{-1}			
E I/A	Magnetic form factor	mm ⁻¹			
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	S			
ω	Angular frequency; $\omega = 2 \Pi f$	s-1			

All dimensions are given in mm.

Surface-mount device



Important notes

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Important notes

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